



NO: RD-IH-SD189-A

DATE: 2012/07/12 R (REV:A2)

1000 BASE-T MAGNETICS MODULES

MODEL NO.: IH-189-A

FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C/ 3~5 Sec

Do not use material and use that the prohibition that SS-00259 stipulates

Designed to meet IR requirement

Operating temp. : -40°C TO +85°C

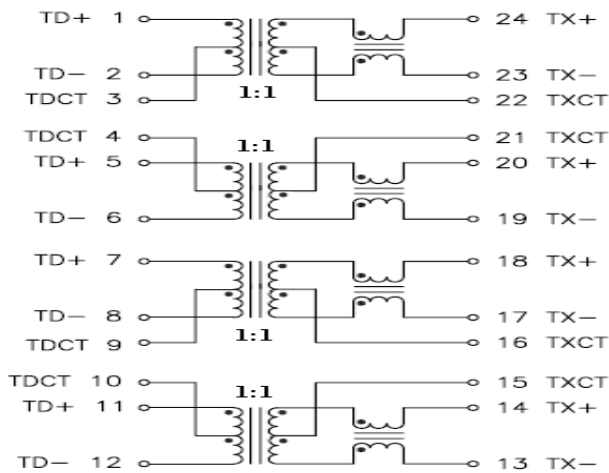
Specifications @ 25°C

OCL : 350 uH Min. @100kHz ,100mv

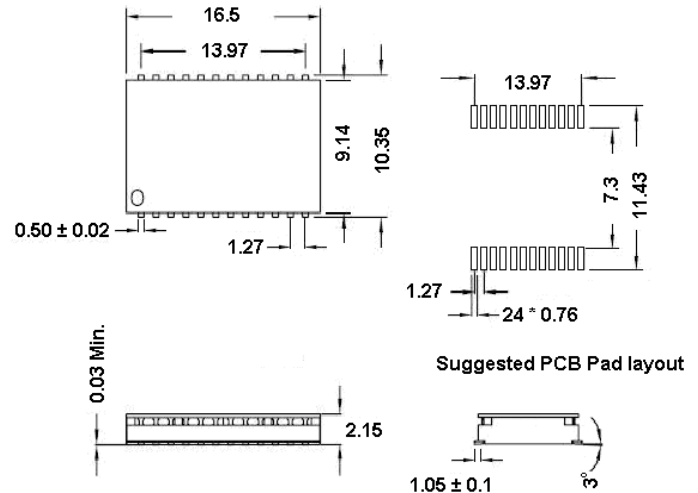
MSL=2

Part Number	Insertion Loss (dB MAX)	Return Loss (dB Min @100Ω)			Differential to Common Mode Rejection (dB MIN)	Cross talk (dB MIN)		
IH-189-A	1~100 MHz	1-40	50	60-80 MHz	1 ~ 100 MHz	30	60	100 MHz
	-1.0	-18	-14	-12	-33	-45	-40	-35

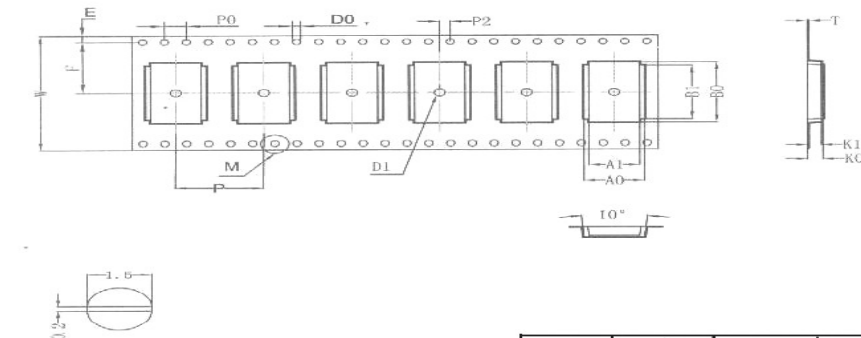
SCHEMATICS:



DIMENSION: mm TOLERANCE:±0.25



Packing :



ITEM	W	A ₀	A ₁	B ₀	B ₁	K ₀	K ₁	P	F	T
DIM	32.0 ^{+0.20} _{-0.20}	11.5 ^{+0.10} _{-0.10}	9.30 ^{+0.10} _{-0.10}	16.8 ^{+0.10} _{-0.10}	15.0 ^{+0.10} _{-0.10}	2.80 ^{+0.10} _{-0.10}	2.50 ^{+0.10} _{-0.10}	16.0 ^{+0.10} _{-0.10}	14.2 ^{+0.10} _{-0.10}	0.30 ^{+0.05} _{-0.05}

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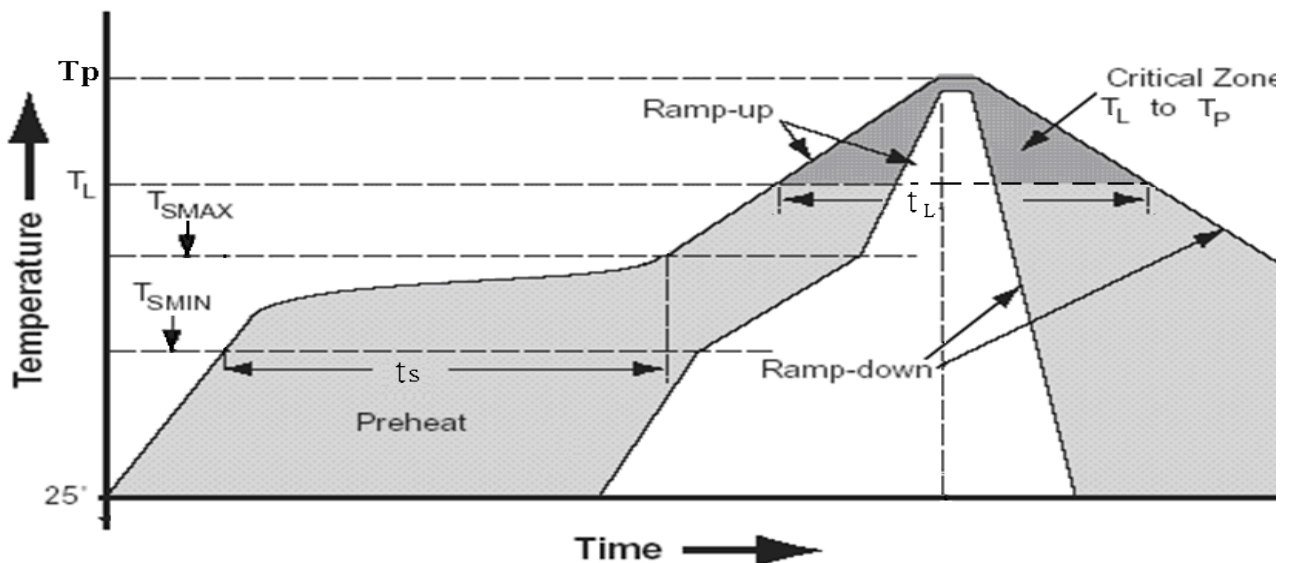
Solder Reflow profile for Lead-Free packages.

Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (t_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Temperature (T_p)	260 +0 / -5 °C	250 +0 / -5 °C
Time within 5 °C of actual peak Temp.	3 to 5 Sec	20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

Profile





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PACKING

1. Tape & Reel : 800pcs / Reel , 4000pcs / Carton
2. Dry Pack : 1pcs
Product Description:(5g Silica Gel Desiccant)
PH: 4-8
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per JEDEC

